



US 20230231538A1

(19) **United States**(12) **Patent Application Publication**
OJA(10) **Pub. No.: US 2023/0231538 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **MEMS RESONATOR AND
MANUFACTURING METHOD****Publication Classification**(51) **Int. Cl.****H03H 9/24** (2006.01)**H03H 3/007** (2006.01)**H03H 9/02** (2006.01)(52) **U.S. Cl.**CPC **H03H 9/2452** (2013.01); **H03H 3/0072**
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§ 371 (c)(1),

(2) Date: **Dec. 19, 2022**(30) **Foreign Application Priority Data**

Jul. 3, 2020 (FI) 20205711

(57)

ABSTRACT

A MEMS (microelectromechanical system) resonator includes a first layer of single-crystalline silicon, a second layer of single-crystalline silicon, and a piezoelectric layer in between said first layer of single-crystalline silicon and the second layer of single-crystalline silicon. A manufacturing method of the MEMS resonator includes at least one of the interfaces between the single-crystalline silicon layers and the piezoelectric layer be made by wafer bonding.

